

3310GJ-VB Datasheet

P-Channel 30-V (D-S) MOSFET

PRODUCT SUMMARY						
V _{DS} (V)	$R_{DS(on)}(\Omega)$	I _D (A) ^d	Q _g (Typ.)			
- 30	0.056at V _{GS} = - 10 V	- 20	19 nC			
- 30	0.072 at V _{GS} = - 4.5 V	- 15	19110			

TO-251

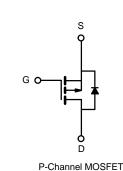
FEATURES

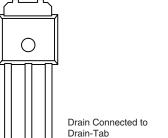
- Halogen-free
- Trench Power MOSFET
- 100 % R_g Tested
- 100 % UIS Tested



APPLICATIONS

- Load Switch
- · Notebook Adaptor Switch





D Top View

G

Parameter	Symbol	Limit	Unit	
Drain-Source Voltage	V _{DS}	- 30	V	
Gate-Source Voltage		V_{GS}	± 20	V
	T _C = 25 °C		- 20	
Continuous Drain Current (T ₁ = 150 °C)	T _C = 70 °C		- 15	
Continuous Diam Curient (1) = 130 °C)	T _A = 25 °C	l _D	-7.9 ^{a, b}	
	T _A = 70 °C		- 5.6 ^{a, b}	
Pulsed Drain Current	I _{DM}	- 60	A	
Continuous Source-Drain Diode Current	T _C = 25 °C		- 20	
Continuous Source-Drain Diode Current	T _A = 25 °C	ls -	- 7.9 ^{a, b}	
Avalanche Current	1 0.4 ml l	I _{AS}	- 20	
Single-Pulse Avalanche Energy	L = 0.1 mH	E _{AS}	20	mJ
	T _C = 25 °C		20	

THERMAL RESISTANCE RATINGS						
Parameter		Symbol	Typical	Maximum	Unit	
Maximum Junction-to-Ambient ^{a, c}	t ≤ 10 s	R_{thJA}	38	46	°C/W	
Maximum Junction-to-Foot	Steady State	R _{thJF}	20	25	C/VV	

T_C = 70 °C

T_A = 25 °C

 $\overline{T_A} = 70 \, ^{\circ}C$

 P_{D}

 T_J, T_{stq}

Notes:

- a. Surface mounted on 1" x 1" FR4 board.
- b. t = 10 s.
- c. Maximum under Steady State conditions is 85 °C/W.

Operating Junction and Storage Temperature Range

d. Based on T_C = 25 °C.

Maximum Power Dissipation

W

°C

15

2.7^{a, b}

1.7^{a, b}

- 55 to 150



Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit
Static						
Drain-Source Breakdown Voltage	V _{DS}	$V_{GS} = 0 \text{ V}, I_D = -250 \mu\text{A}$	- 30			V
V _{DS} Temperature Coefficient	$\Delta V_{DS}/T_{J}$	I _D = - 250 μA		- 34		mV/
V _{GS(th)} Temperature Coefficient	$\Delta V_{GS(th)}/T_J$			5.3		°C
Gate-Source Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_{D} = -250 \mu A$	- 1.4		- 2.5	V
Gate-Source Leakage	I _{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 25 \text{ V}$			± 100	nA
Zara Cata Valtaga Drain Current	I _{DSS}	V _{DS} = - 30 V, V _{GS} = 0 V V _{DS} = - 30 V, V _{GS} = 0 V, T _J = 55 °C			- 1	μΑ
Zero Gate Voltage Drain Current					- 5	
On-State Drain Current ^a	I _{D(on)}	$V_{DS} \ge -10 \text{ V}, V_{GS} = -10 \text{ V}$	- 20			Α
David Course On Otata Basista and	D	V _{GS} = - 10 V, I _D = - 6 A		0.056		Ω
Drain-Source On-State Resistance ^a	R _{DS(on)}	V _{GS} = - 4.5 V, I _D = - 4 A		0.072		
Forward Transconductance ^a	9 _{fs}	V _{DS} = - 10 V, I _D = - 6 A		28		S
Dynamic ^b						
Input Capacitance	C _{iss}			1150		pF
Output Capacitance	C _{oss}	$V_{DS} = -15 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$		205		
Reverse Transfer Capacitance	C _{rss}			140		
Total Gate Charge	Q_g $V_{DS} = -15 \text{ V}, V_{GS} = -10 \text{ V}, I_D = -6 \text{ A}$	$V_{DS} = -15 \text{ V}, V_{GS} = -10 \text{ V}, I_{D} = -6 \text{ A}$		27	43	200
				19	25	
Gate-Source Charge	Q_{gs} $V_{DS} = -15 \text{ V}, V_{GS} = -4.5 \text{ V}, I_D = -6 \text{ A}$			6		nC
Gate-Drain Charge	Q _{gd}			12		1
Gate Resistance	R _g	f = 1 MHz	0.5	2.2	4.4	Ω
Turn-On Delay Time	t _{d(on)}			13	25	
Rise Time	t_r $V_{DD} = -15 \text{ V}, R_L = 1.5 \Omega$			12	24	
Turn-Off DelayTime	t _{d(off)}	$I_D \cong$ - 10 A, V_{GEN} = - 10 V, R_g = 1 Ω		40	70	
Fall Time	t _f			9	18	
Turn-On Delay Time	t _{d(on)}			48	80	ns
Rise Time	t _r	$V_{DD} = -15 \text{ V}, R_{L} = 1.5 \Omega$		92	160	
Turn-Off DelayTime	$t_{d(off)}$ $I_D \cong -6$ A, $V_{GEN} = -4.5$ V, $R_g = 1$ Ω			34	60	1
Fall Time	t _f			19	35	1
Drain-Source Body Diode Characteris	tics					•
Continous Source-Drain Diode Current	I _S	T _C = 25 °C			- 4.1	۸
Pulse Diode Forward Current	I _{SM}				- 60	_ A
Body Diode Voltage	V _{SD}	I _S = - 3 A, V _{GS} = 0 V		- 0.75	- 1.2	V
Body Diode Reverse Recovery Time				27	45	ns
Body Diode Reverse Recovery Charge	Q _{rr}	L _ 6 A dl/dt _ 100 A/vs T		16	27	nC
Reverse Recovery Fall Time	t _a	$I_F = -6 \text{ A}, \text{ dI/dt} = 100 \text{ A/}\mu\text{s}, T_J = 25 ^{\circ}\text{C}$		12		ns
Reverse Recovery Rise Time	t _b	1		15		

Notes:

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

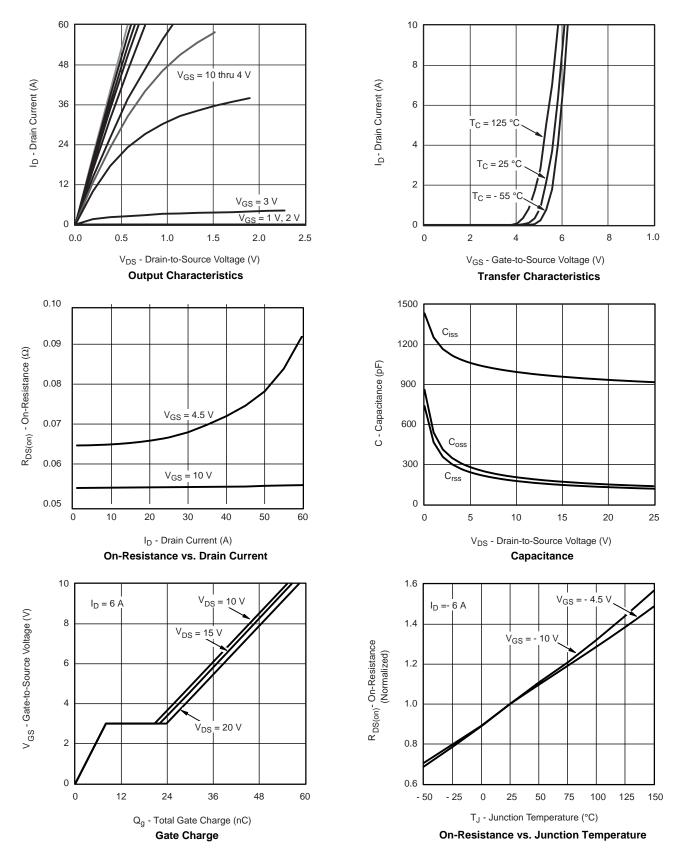
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a. Pulse test; pulse width $\leq 300~\mu s,$ duty cycle $\leq 2~\%.$

b. Guaranteed by design, not subject to production testing.

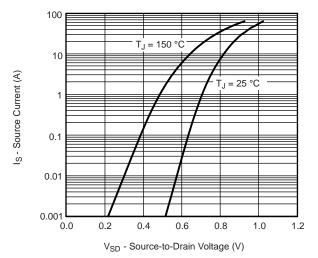


TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

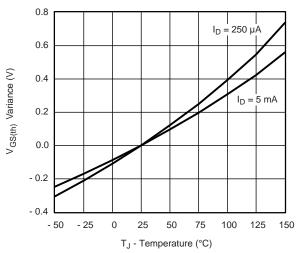




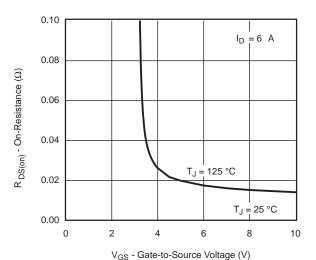
TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



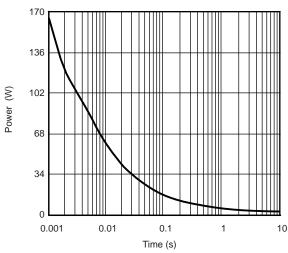
Source-Drain Diode Forward Voltage



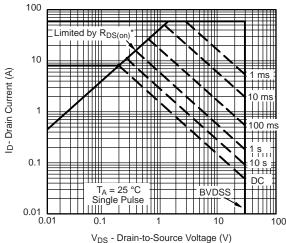
Threshold Voltage



On-Resistance vs. Gate-to-Source Voltage



Single Pulse Power, Junction-to-Ambient

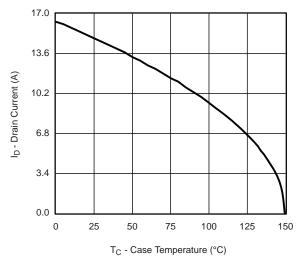


V_{DS} - Drain-to-Source voltage (V)
V_{GS} > minimum V_{GS} at which R_{DS(on)} is specified

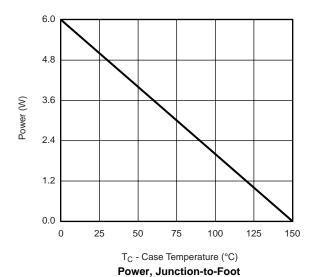
Safe Operating Area

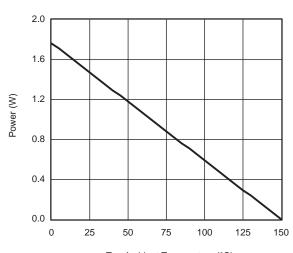


MOSFET TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



Current Derating*





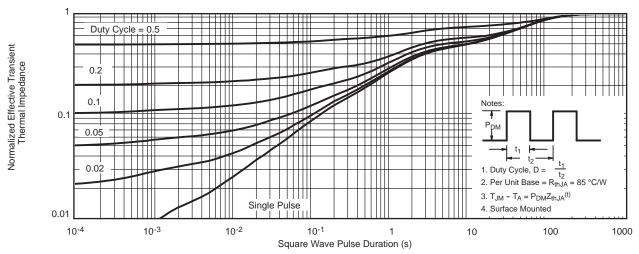
T_A - Ambient Temperature (°C) Power Derating, Junction-to-Ambient

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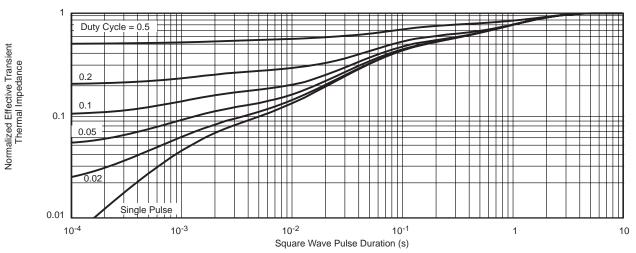
^{*} The power dissipation P_D is based on $T_{J(max)}$ = 150 °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package



TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



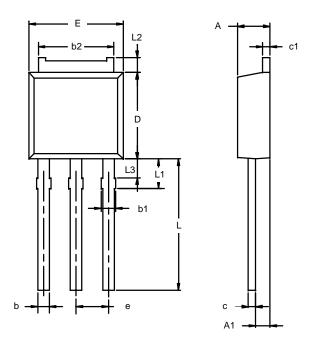
Normalized Thermal Transient Impedance, Junction-to-Ambient



Normalized Thermal Transient Impedance, Junction-to-Foot



TO-251AA



Note: Dimension L3 is for reference only.

	MILLIM	IETERS	INC	HES	
Dim	Min	Max	Min	Max	
Α	2.21	2.38	0.087	0.094	
A 1	0.89	1.14	0.035	0.045	
b	0.71	0.89	0.028	0.035	
b1	0.76	1.14	0.030	0.045	
b2	5.23	5.43	0.206	0.214	
С	0.46	0.58	0.018	0.023	
с1	0.46	0.58	0.018	0.023	
D	5.97	6.22	0.235	0.245	
Е	6.48	6.73	0.255	0.265	
е	2.28 BSC		0.090 BSC		
L	3.89	9.53	0.153	0.375	
L1	1.91	2.28	0.075	0.090	
L2	0.89	1.27	0.035	0.050	
L3	1.15	1.52	0.045	0.060	

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